



AMT-1

(ATLAS Muon TDC version 1)

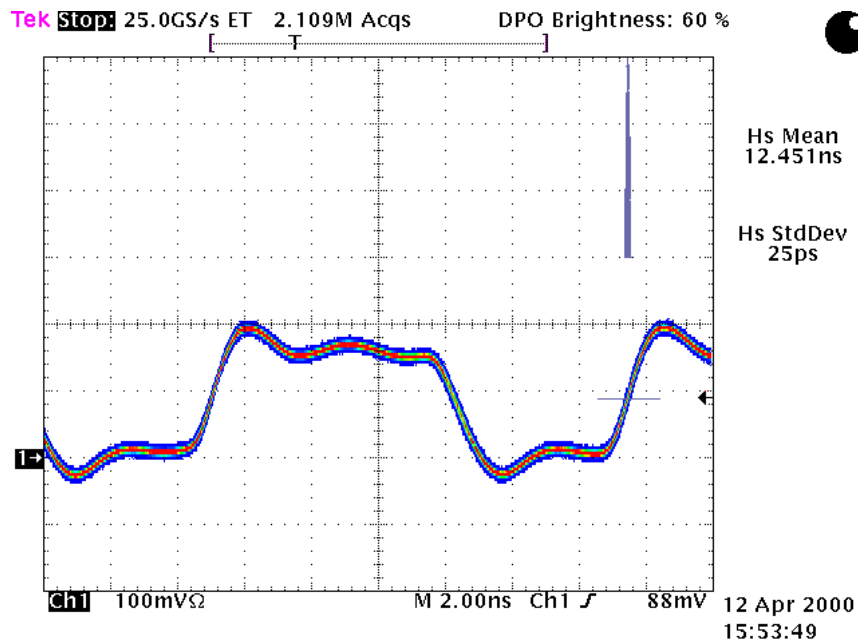
Data Sheets

Yasuo Arai

KEK, National High Energy Accelerator Research Organization
1-1 Oho, Tsukuba, Ibaraki 305, Japan
yasuo.arai@kek.jp, <http://atlas.kek.jp/~arai/>
Tel : +81-298-64-53
66, Fax : +81-298-64-2580

Chip designed on Mar, 2000

Rev. 0.1 Oct. 10, 2000.



Contents

- 1. SIGNAL, PACKAGE AND PIN ASSIGNMENT..... 3**
 - 1.1. SIGNAL DESCRIPTION..... 3
 - 1.2. PIN ASSIGNMENT 4
 - 1.3. PACKAGE 6

- 2. ELECTRICAL CHARACTERISTICS..... 7**
 - 2.1. MAXIMUM RATINGS 7
 - 2.2. RECOMMENDED OPERATING CONDITION..... 7
 - 2.3. DC CHARACTERISTICS 7
 - 2.4. AC CHARACTERISTICS10
 - 2.4.1. *Clock Signal Characteristics (pll_multi=0)*.....10
 - 2.4.2. *CSR Access Timing*.....11
 - 2.4.3. *JTAG Timing*.....12
 - 2.4.4. *Serial Output Timing*.....13

1. Signal, Package and Pin Assignment

1.1. Signal description

Table. 1. Signal description.

Name	I/O	Description
RESETP / $\overline{\text{RESETM}}$	LVI	Reset signal.
ENCCONTP / $\overline{\text{ENCCONTM}}$	LVI	Encoded Control Signal.
HITP0 - 23 / $\overline{\text{HITM0 - 23}}$	LVI	Hit inputs.
BUNCHRSTP / $\overline{\text{BUNCHRSTM}}$	LVI	Bunch Count Reset signal.
EVENTRSTP / $\overline{\text{EVENTRSTM}}$	LVI	Event Count Reset signal.
TRIGP / $\overline{\text{TRIGM}}$	LVI	Trigger signal.
CLKP / $\overline{\text{CLKM}}$	LVI	System clock input.
CDIO0 - 11	I, TO	CSR data lines and Parallel data output[11:0]
CDIO12 - 31	TO	Parallel data output[31:12]
DREADY	O	Data Ready signal.
ERROR	O	Error signal
CLKOUT	O	PLL Clock, Start and Carry output signal. Controlled by clkout_mode bits.
TEST0 - 1	I, PD	Test mode select inputs. TEST=0 : Normal MDe TEST=1 : Toshiba standard test mode, TEST=2 : IDDS test mode, TEST=3 : Test clock mode.
TDO	TO	JTAG TDO.
TMS	I, PU	JTAG TMS.
TDI	I, PU	JTAG TDI.
TCK	I	JTAG TCK.
$\overline{\text{TRSTB}}$	I, PU	JTAG $\overline{\text{TRSTB}}$.
GETDATA	I	Get Data signal.
START	I	Start signal. Start coarse counter and enable channel inputs.
SERIOUTP / $\overline{\text{SERIOUTM}}$	LVO	Serial data output.
STROBEP / $\overline{\text{STROBEM}}$	LVO	Serial strobe output.
DSPACE	I	Data Space select signal. DSPACE = 1 : Parallel data, DSPACE = 0 : CSR space.
WR	I	CSR write signal.
CS	I	Chip Select signal.
RA0 - 4	I	CSR address signal
VGN	analog	PLL loop filter terminal. This pin should be connected to external capacitors of 6800 pF.

[I = CMOS Input, LVI = LVDS Input, O = CMOS Output, TO = Three State Output, LVO = LVDS Output; PU = with internal pull-up resistor, PD = with internal pull-down resistor, $\overline{\text{xxx}}$ = negative logic]

* LVDS input has a internal 100 ohm termination resistor.

1.2. Pin Assignment

Pin #	Name	Interface
1=	RESETM	WLVD SIN
2=	RESETP	WLVD SIN
3=	ENCCONTM	WLVD SIN
4=	ENCCONTP	WLVD SIN
5=	VDD	
6=	VSS	
7=	HITM0	WLVD SIN
8=	HITP0	WLVD SIN
9=	HITM1	WLVD SIN
10=	HITP1	WLVD SIN
11=	HITM2	WLVD SIN
12=	HITP2	WLVD SIN
13=	HITM3	WLVD SIN
14=	HITP3	WLVD SIN
15=	HITM4	WLVD SIN
16=	HITP4	WLVD SIN
17=	VSS	
18=	VDD	
19=	HITM5	WLVD SIN
20=	HITP5	WLVD SIN
21=	HITM6	WLVD SIN
22=	HITP6	WLVD SIN
23=	HITM7	WLVD SIN
24=	HITP7	WLVD SIN
25=	HITM8	WLVD SIN
26=	HITP8	WLVD SIN
27=	HITM9	WLVD SIN
28=	HITP9	WLVD SIN
29=	VDD	
30=	VSS	
31=	HITM10	WLVD SIN
32=	HITP10	WLVD SIN
33=	HITM11	WLVD SIN
34=	HITP11	WLVD SIN
35=	HITM12	WLVD SIN
36=	HITP12	WLVD SIN

Pin #	Name	Interface
37=	HITM13	WLVD SIN
38=	HITP13	WLVD SIN
39=	HITM14	WLVD SIN
40=	HITP14	WLVD SIN
41=	VDD	
42=	HITM15	WLVD SIN
43=	HITP15	WLVD SIN
44=	VSS	
45=	HITM16	WLVD SIN
46=	HITP16	WLVD SIN
47=	HITM17	WLVD SIN
48=	HITP17	WLVD SIN
49=	HITM18	WLVD SIN
50=	HITP18	WLVD SIN
51=	HITM19	WLVD SIN
52=	HITP19	WLVD SIN
53=	VDD	
54=	VSS	
55=	HITM20	WLVD SIN
56=	HITP20	WLVD SIN
57=	HITM21	WLVD SIN
58=	HITP21	WLVD SIN
59=	HITM22	WLVD SIN
60=	HITP22	WLVD SIN
61=	HITM23	WLVD SIN
62=	HITP23	WLVD SIN
63=	VDD	
64=	VSS	
65=	BUNCHRSTM	WLVD SIN
66=	BUNCHRSTP	WLVD SIN
67=	EVENTRSTM	WLVD SIN
68=	EVENTRSTP	WLVD SIN
69=	TRIGM	WLVD SIN
70=	TRIGP	WLVD SIN
71=	CLKM	WLVD SIN
72=	CLKP	WLVD SIN

Pin #	Name	Interface
73=	VSS	
74=	VDD	
75=	CDIO0	BD8RC
76=	CDIO1	BD8RC
77=	CDIO2	BD8RC
78=	CDIO3	BD8RC
79=	CDIO4	BD8RC
80=	CDIO5	BD8RC
81=	CDIO6	BD8RC
82=	VSS	
83=	CDIO7	BD8RC
84=	CDIO8	BD8RC
85=	CDIO9	BD8RC
86=	CDIO10	BD8RC
87=	CDIO11	BD8RC
88=	DIO12	BT8R
89=	DIO13	BT8R
90=	VDD	
91=	DIO14	BT8R
92=	DIO15	BT8R
93=	DIO16	BT8R
94=	DIO17	BT8R
95=	DIO18	BT8R
96=	DIO19	BT8R
97=	DIO20	BT8R
98=	VSS	
99=	DIO21	BT8R
100=	DIO22	BT8R
101=	DIO23	BT8R
102=	DIO24	BT8R
103=	DIO25	BT8R
104=	DIO26	BT8R
105=	DIO27	BT8R
106=	VDD	
107=	DIO28	BT8R
108=	DIO29	BT8R

Pin #	Name	Interface
109=	DIO30	BT8R
110=	DIO31	BT8R
111=	DREADY	B4R
112=	ERROR	B4R
113=	CLKOUT	B8R
114=	TEST0	IBUFD
115=	TDO	BT4
116=	VSS	
117=	VDD	
118=	TMS	IBUFU
119=	TDI	IBUFU
120=	TCK	IBUF
121=	TRSTB	IBUFU
122=	GETDATA	IBUF
123=	START	IBUF
124=	VSS	
125=	SERIOUTP	WLVDOUT
126=	SERIOUTM	WLVDOUT
127=	STROBEP	WLVDOUT
128=	STROBEM	WLVDOUT
129=	VDD	
130=	TEST1	IBUFD
131=	DSPACE	IBUF
132=	WR	IBUF
133=	CS	IBUF
134=	RA0	IBUF
135=	RA1	IBUF
136=	VSS	
137=	RA2	IBUF
138=	RA3	IBUF
139=	RA4	IBUF
140=	VDD	
141=	VSS	
142=	VGN	WDOUT
143=	VSS	
144=	VDD	

1.3.Package

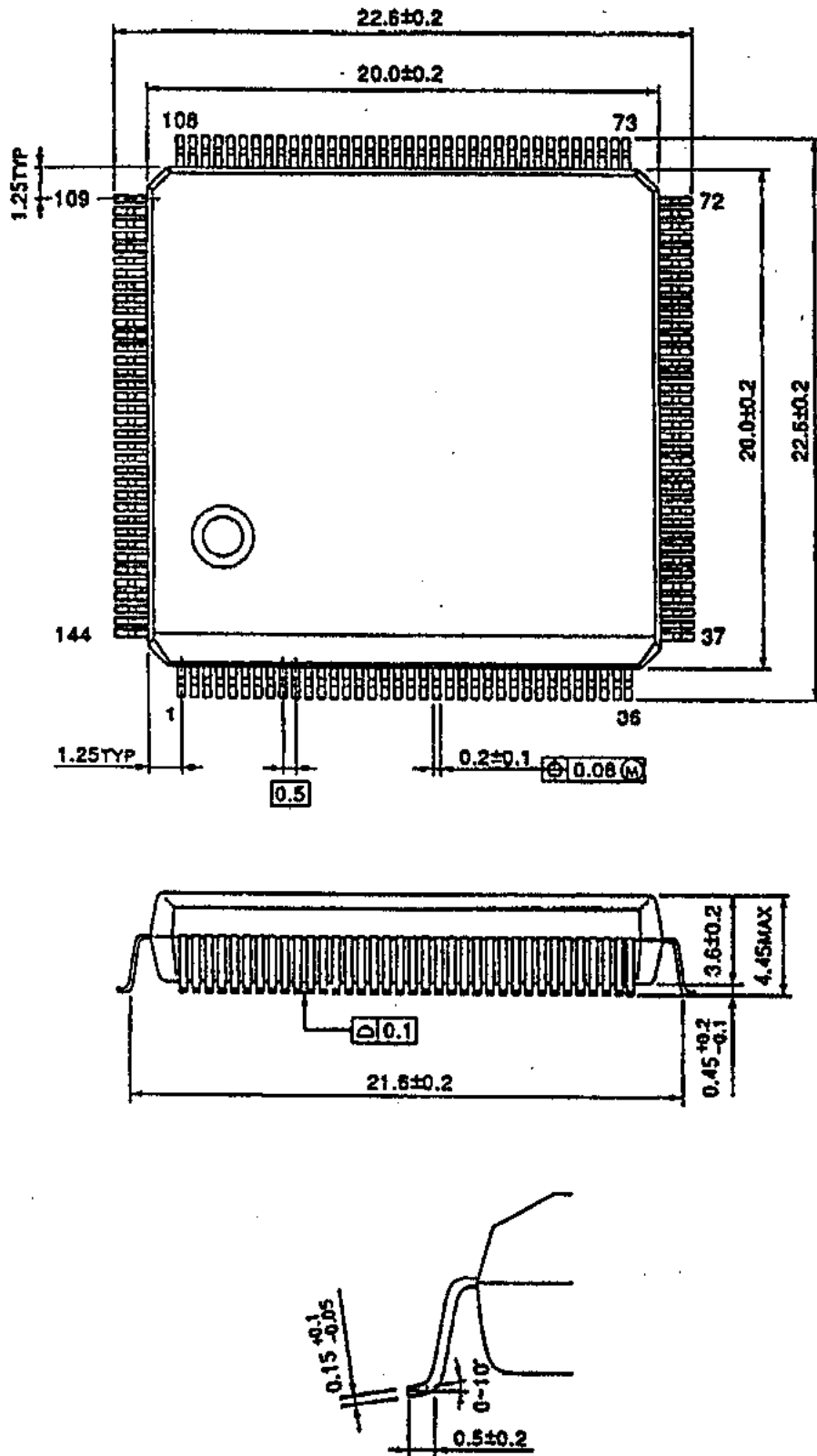


Fig. 1 QFP144 : 144-pin Plastic Flat Package

2. Electrical Characteristics

2.1. Maximum Ratings

Symbol	Parameter	Value
VDD	DC Supply Voltage	-0.3 to +5.0 V
VIN	Input Voltage	-0.3 to VDD+0.3 V
IIN	Input Current	±10 mA
T _{STG}	Storage Temperature	-40 to +125 °C

2.2. Recommended Operating Condition

(VSS = 0V)

Symbol	Parameter	Value
VDD	DC Supply Voltage	3.3 to 3.8 V
VIN	Input Voltage	VDD
Ta	Ambient Temperature	0 to +85 °C

2.3. DC Characteristics

Symbol	Parameter	Condition	Min.	Max.	Unit
V _{IH}	Input High Voltage		V _{DD} x 0.8		
V _{IL}	Input Low Voltage			V _{DD} x 0.2	
I _{IH}	Input High Current	V _{IN} = V _{DD}	-10	10	μA
	(with pull down resistor)		-10	200	μA
I _{IL}	Input Low Current	V _{IN} = V _{SS}	-10	10	μA
	(with pull up resistor)		-200	10	μA
V _{OH}	High-level output voltage	I _{OH} = -4mA (B4: DREADY, ERROR, CLKOUT, TDO)	2.4		V
		I _{OH} = -8mA (B8: CDIO0-31)	2.4		V
V _{OL}	Low-level output voltage	I _{OH} =4mA (B4: DREADY, ERROR, CLKOUT, TDO)		0.4	V
		I _{OH} = 8mA (B8: CDIO0-31)		0.4	V
I _{OZ}	3-state output leakage current	V _{OUT} = V _{DD} or V _{SS}	-10	10	μA
I _{DD5}	Quiescent device current(*)	V _{IN} = V _{DD} or V _{SS} (TEST0 = 0, TEST1 = 1)		400	μA

(*) At present design, charge pump circuit in PLL is not cut off in the IDDS mode (TEST=2).

LVDS Input & Output

Symbol	Parameter	Condition	Min	Max	Unit
V _{OD}	Differential output voltage	R _L =100Ω	200	400	mV
V _{OC}	Common-mode output voltage	R _L =100Ω	0.9	1.4	V
V _I	Input voltage range		0	1.9	V

$ V_{ID} $	Differential input voltage	(*)	200		mV
V_{ICM}	Input common mode voltage		50	1800	mV

(*) LVDS receiver contains an internal 100 ohm termination resistor.

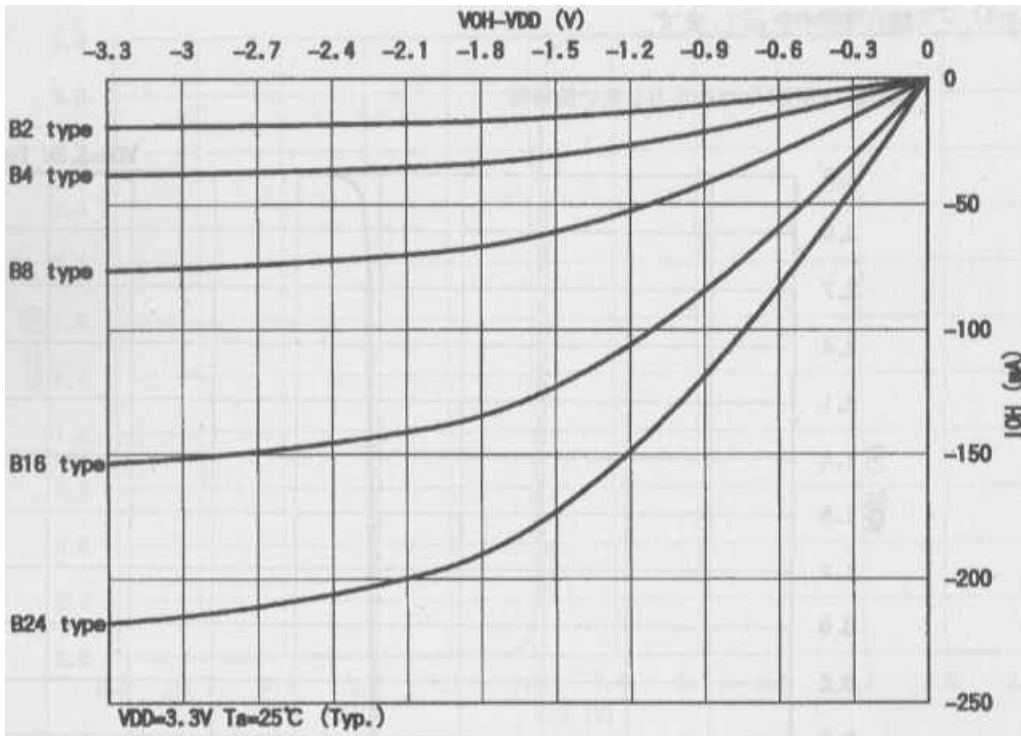


Fig. 2. Output Buffer V_{OH} - I_{OH} characteristics.

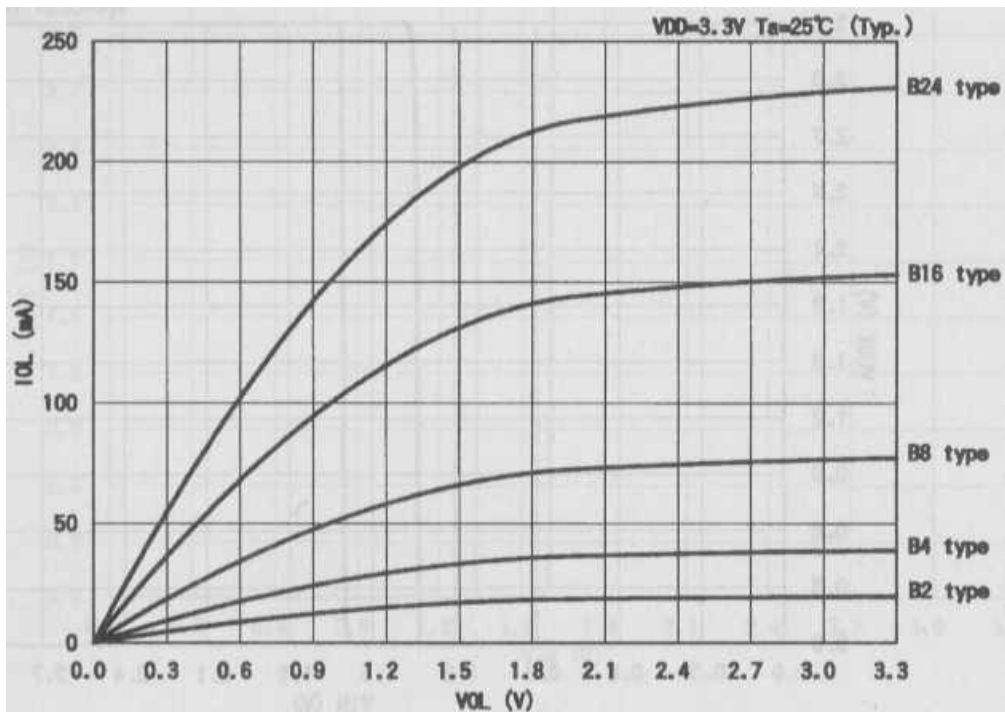


Fig. 3. Output Buffer V_{OL} - I_{OL} characteristics.

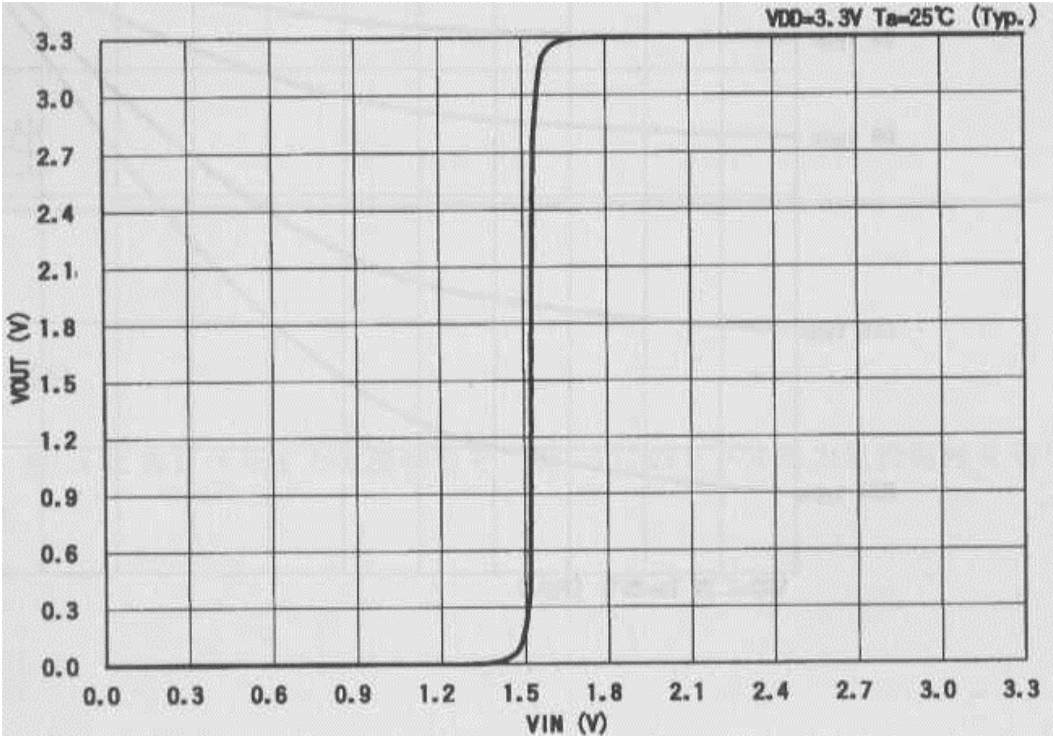


Fig. 4. CMOS Input Buffer characteristic.

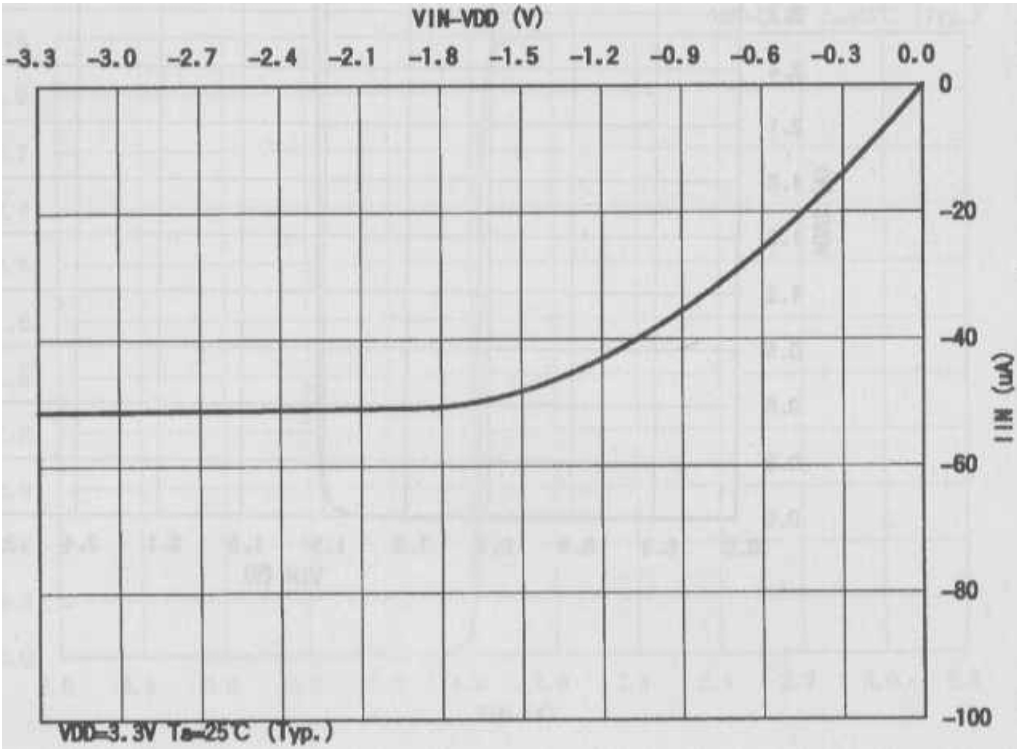


Fig. 5. Characteristic of Input buffer with Pull Up resistor.

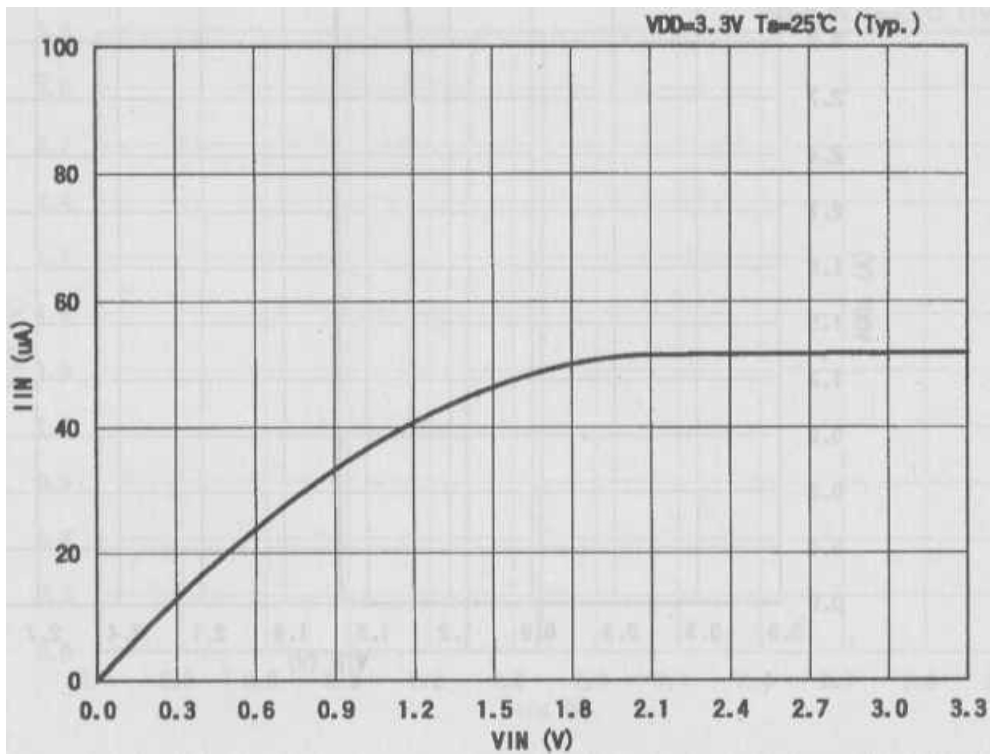


Fig. 6. Characteristic of Input Buffer with Pull Down resistor.

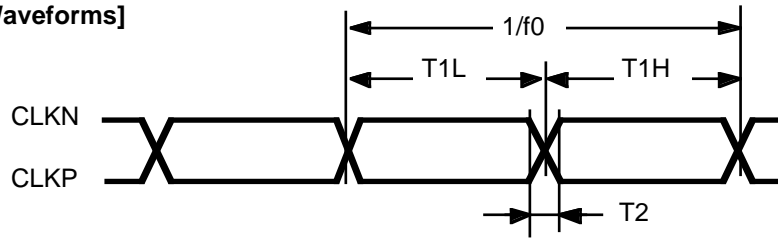
2.4.AC Characteristics

(VDD = 3.3 V, Ta = 25 °C, C_L = 30pF)

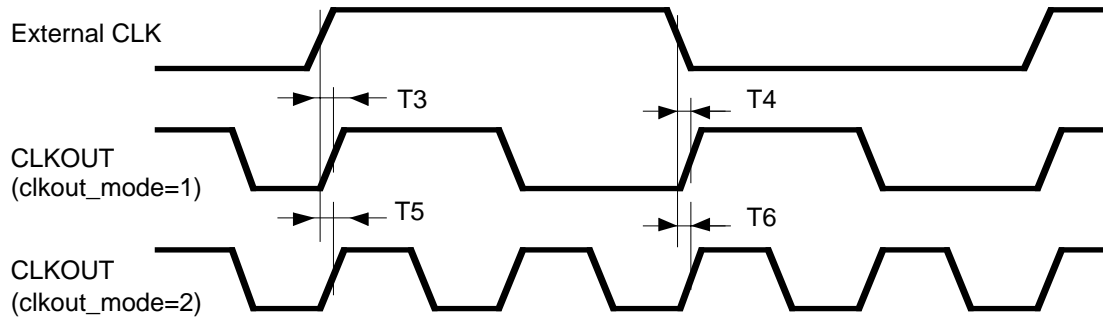
2.4.1.Clock Signal Characteristics (pll_multi=0)

Symbol	Characteristics	Condition	Min	Typ	Max	Unit
f0	CLK frequency			40	60	MHz
T1L/T1H	CLK duty factor		0.8	1	1.25	
T3	CLK transition time				2	ns
T4	External clock and CLKOUT phase offset	clkout_mode=1				ns
T5	External clock and CLKOUT phase offset	clkout_mode=1				ns
T6	External clock and CLKOUT phase offset	clkout_mode=2				ns
T7	External clock and CLKOUT phase offset	clkout_mode=2				ns

[Clock Waveforms]



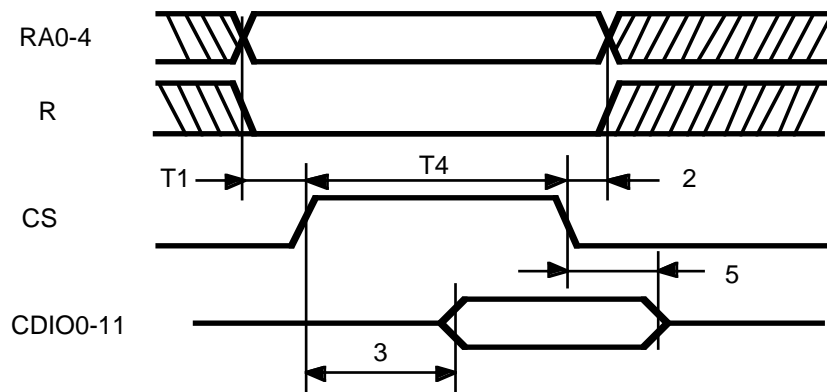
[Clock Offsets] (PII_multi=0)



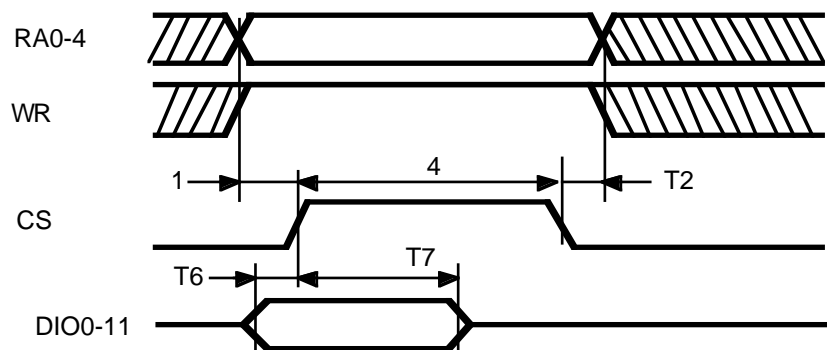
2.4.2.CSR Access Timing

Symbol	Characteristics	Min	Max	Unit
T1	RAX, WR setup time	1		ns
T2	CS negate to RAX, WR negate time	2		ns
T3	CS asserted to CDIOx asserted		17	ns
T4	CS pulse width	8		ns
T5	CS negated to CDIOx negated		10	ns
T6	CDIO0-11 setup time	-1		ns
T7	CDIO0-11 hold time	9		ns

[CSR Read Cycle Timing Diagram]



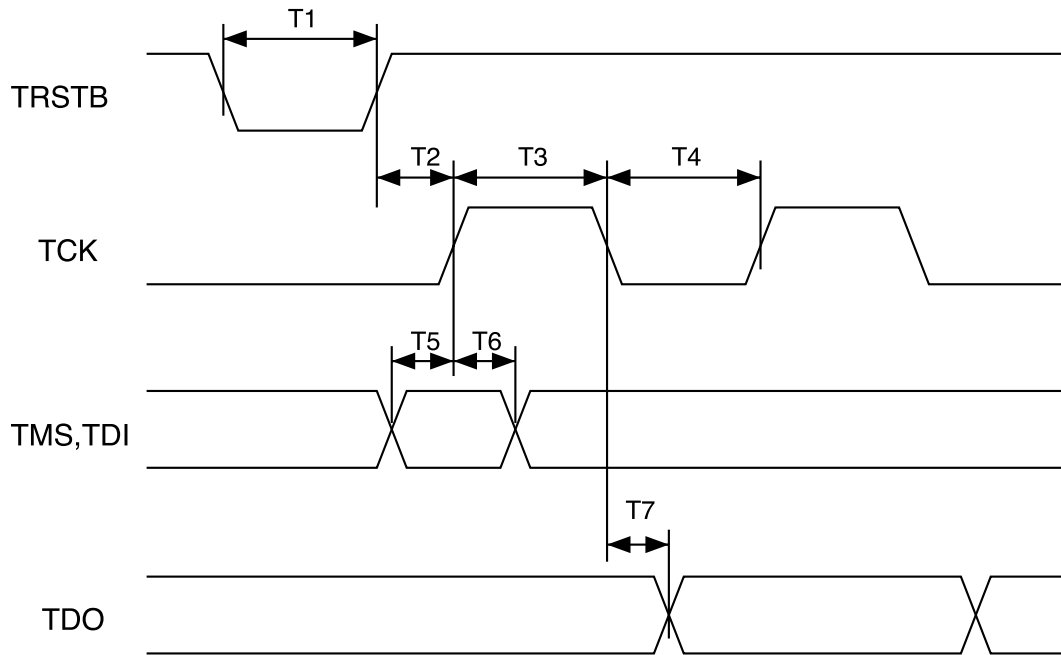
[CSR Write Cycle Timing Diagram]



2.4.3.JTAG Timing

Symbol	Characteristics	Min	Max	Unit
T1	TRSTB width	4		ns
T2	TRSTB negate to TCK assert	3		ns
T3	TCK high width	6		ns
T4	TCK low width	6		ns
T5	TMS,TDI setup time	2		ns
T6	TMS,TDI hold time	2		ns
T7	TDO delay		8	ns

[JTAG Timing]



2.4.4. Serial Output Timing

Symbol	Characteristics	Condition	Min	Max	Unit
T1	SERIOUT-STROBE timing (leading strobe)	readout_speed=0(40Mbps)	-	-	ns
		readout_speed=1(20Mbps)	-	-	ns
		readout_speed=2(10Mbps)	-	-	ns
		readout_speed=3(80Mbps)	-0.5	1.5	ns
T2	SERIOUT-STROBE timing (DS strobe)	readout_speed=0(40Mbps)	-0.5	2	ns
		readout_speed=1(20Mbps)	-0.5	2	ns
		readout_speed=2(10Mbps)	-0.5	2	ns
		readout_speed=3(80Mbps)	-0.5	2	ns
T3	CLKOUT-STROBE timing (clkout_mode=2)	readout_speed=0(40Mbps)	3	5	ns
		readout_speed=1(20Mbps)	3	5	ns
		readout_speed=2(10Mbps)	3	5	ns
		readout_speed=3(80Mbps)	1.5	3.5	ns

